



DUAL P-CHANNEL 60V ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D T _A = +25°C (Notes 4 & 6)
<u> </u>	85mΩ @ V _{GS} = -10V	-3.9A
-60V	125mΩ @ V _{GS} = -4.5V	-3.2A

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions

SO-8

- Disconnect Switches
- Motor Control

Features

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Low Profile SOIC Package
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Available

Mechanical Data

Case: SO-8

🗆 D1

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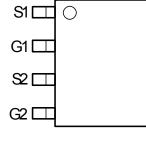
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 $\Box D2$

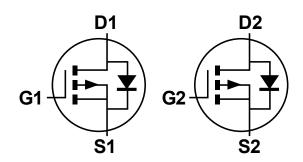
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (approximate)



Top View







Equivalent Circuit

Ordering Information

Notes:

Part Number	Qualification	Case	Packaging
ZXMP6A16DN8QTA	Automotive	SO-8	500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

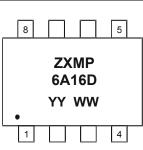
 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

 Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



ZXMP6A16D = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 11 = 2011) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source voltage			V _{DSS}	-60	V
Gate-Source voltage (Note 6)		(Note 6)	V _{GS}	±20	V
		(Notes 8 & 10)	ID	-3.9	
Continuous Drain current	V _{GS} = 10V	T _A = +70°C (Notes 8 & 10)		-3.1	А
		(Notes 7 & 10)		-2.9	
Pulsed Drain current		(Notes 9 & 10)	I _{DM}	-18.3	А
Continuous Source current (Body diode)		(Notes 8 & 10)	Is	-3.2	А
Pulsed Source current (Body diode)		(Notes 9 & 10)	I _{SM}	-18.3	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
	(Notes 7 & 10)		1.25 10.0	
Power dissipation Linear derating factor	(Notes 7 & 11)	PD	1.81 14.5	W mW/°C
	(Notes 8 & 10)		2.15 17	
	(Notes 7 & 10)		100	
Thermal Resistance, Junction to Ambient	(Notes 7 & 11)	R _{0JA}	70	80.04
	(Notes 8 & 10)		60	°C/W
Thermal Resistance, Junction to Lead	(Notes 10 & 12)	R _{θJL}	48.85]
Operating and storage temperature range	TJ, T _{STG}	-55 to +150	°C	

Notes:

6. AEC-Q101 V_{SS} maximum is ±16V. 7. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

8. Same as note (7), except the device is measured at t \leq 10 sec.

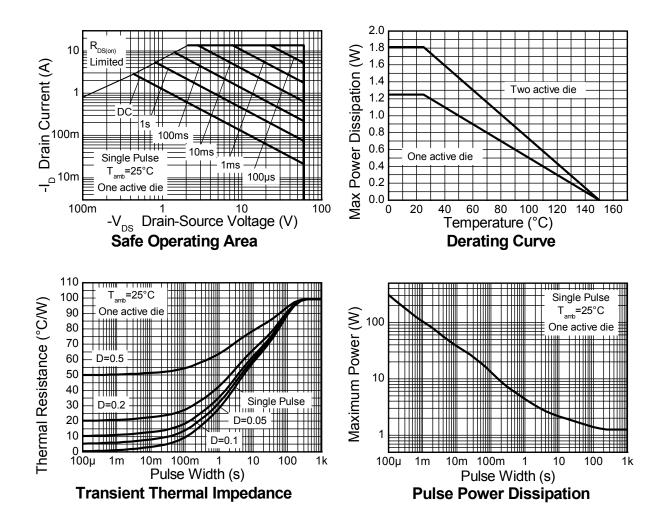
9. Same as note (7), except the device is pulsed with D = 0.02 and pulse width 300μ s. 10. For a dual device with one active die.

11. For a device with two active die running at equal power.
12. Thermal resistance from junction to solder-point.



ZXMP6A16DN8Q

Thermal Characteristics





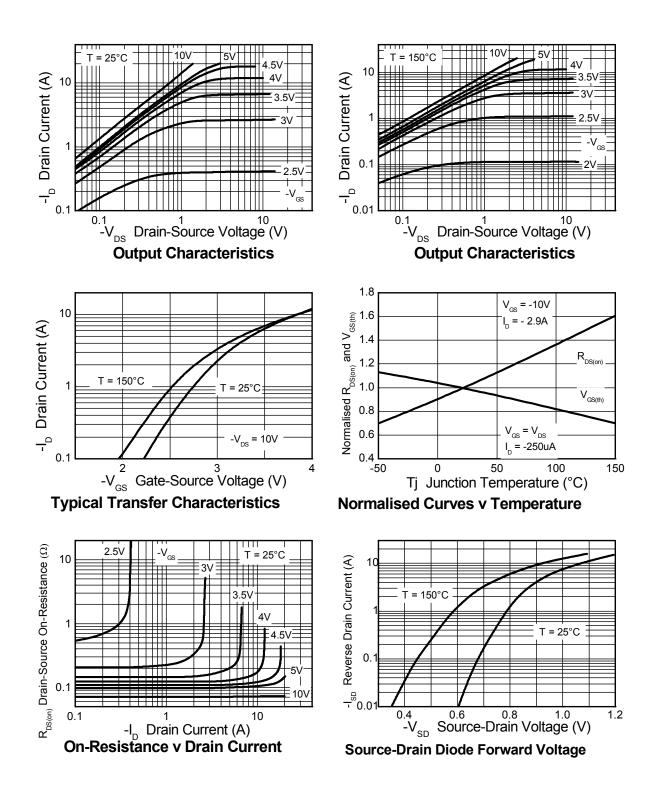
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS				_			
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_	_	V	I _D = -250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	IDSS	_	_	-1.0	μA	V _{DS} = -60V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS			-				
Gate Threshold Voltage	V _{GS(th)}	-1	_		V	I_{D} = -250µA, V_{DS} = V_{GS}	
Static Drain-Source On-Resistance (Note 13)	D		_	85	mΩ	V _{GS} = -10V, I _D = -2.9A	
Static Drain-Source On-Resistance (Note 13)	R _{DS} (ON)	_	_	125	11122	V _{GS} = -4.5V, I _D	= -2.4A
Forward Transconductance (Notes 13 & 14)	g fs	_	7.2	_	S	V _{DS} = -15V, I _D = -2.9A	
Diode Forward Voltage (Note 13)	V _{SD}	_	-0.85	-0.95	V	I_{S} = -3.4A, V_{GS} = 0V, T_{J} = +25°C	
Reverse recovery time (Note 14)	trr	_	29.2	_	ns	I _S = -2A, di/dt = 100A/µs,	
Reverse recovery charge (Note 14)	Qrr	_	39.6	_	nC	T _J = +25°C	
DYNAMIC CHARACTERISTICS (Note 14)			-				
Input Capacitance	C _{iss}	_	1021	_	pF	V _{DS} = -30V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss	_	83.1	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	56.4	—	pF		
Total Gate Charge (Note 15)	Qg	_	12.1	_	nC	V _{GS} = -5V	
Total Gate Charge (Note 15)	Qg	_	24.2	_	nC	V _{DS} = -3	
Gate-Source Charge (Note 15)	Q _{gs}	_	2.5	_	nC	V _{GS} = -10V	I _D = -2.9A
Gate-Drain Charge (Note 15)	Q _{gd}	_	3.7	_	nC]	
Turn-On Delay Time (Note 15)	t _{D(on)}		3.5		ns	V_{DD} = -30V, V_{GS} = -10V, I_D = -1A, $R_G \cong 6\Omega$	
Turn-On Rise Time (Note 15)	tr		4.1		ns		
Turn-Off Delay Time (Note 15)	t _{D(off)}		35	_	ns		
Turn-Off Fall Time (Note 15)	t _f	_	10	_	ns		

Notes:

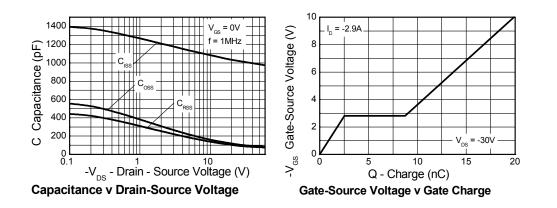


Typical Characteristics

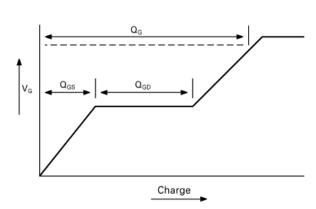




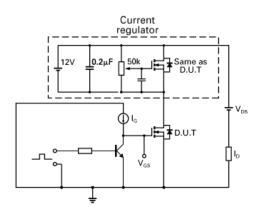
Typical Characteristics (cont.)



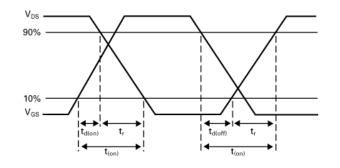
Test Circuits



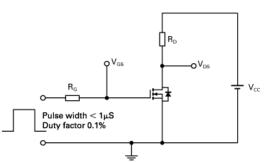
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

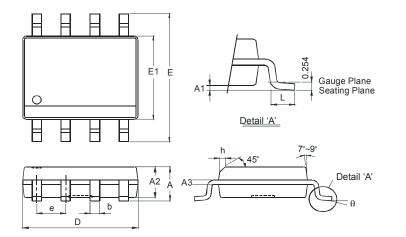


Switching time test circuit



Package Outline Dimensions

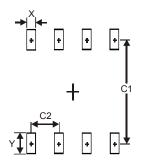
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SO-8					
Dim	Min	Max				
Α	-	1.75				
A1	0.10	0.20				
A2	1.30	1.50				
A3	0.15	0.25				
b	0.3	0.5				
D	4.85	4.95				
E	5.90	6.10				
E1	3.85	3.95				
е	1.27	Тур				
h	-	0.35				
L	0.62	0.82				
θ	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
Х	0.60			
Y	1.55			
C1	5.4			
C2	1.27			



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